

## 40V P-Channel Power MOSFET

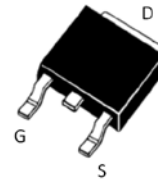
### DESCRIPTION :

- Low on resistance
- Low reverse transfer capacitances
- 100% single pulse avalanche energy test
- 100% $\Delta V_{ds}$  Tested
- RoHS compliant
- Halogen Free

$V_{DS}$	-40V
$I_D (T_C=25^\circ C)$	-85A
$R_{DS(ON\_Typ. @ V_{GS}=-10V}$	6.5m $\Omega$

### TYPICAL APPLICATIONS :

- Power switching applications
- DC-DC converters
- Full bridge control



TO-252

### MAXIMUM RATINGS (at $T_C = 25^\circ C$ , unless otherwise specified)

Characteristic	Condition	Symbol	Value	Unit
Drain-Source Voltage		$V_{DS}$	-40	V
Gate-Source Voltage		$V_{GS}$	$\pm 20$	V
Continuous Drain Current	$T_C=25^\circ C$ $T_C=100^\circ C$	$I_D$	-85 -53	A
Pulsed Drain Current <sup>(1)</sup>	$T_C=25^\circ C$ , $t_p$ limited by $T_{jmax}$	$I_{D\ pulse}$	-338	A
Single Pulsed Avalanche Energy	$L=0.5mH$ , $R_g=25\Omega$	$E_{AS}$	441	mJ
Power dissipation	$T_C=25^\circ C$ $T_A=25^\circ C$	$P_{tot}$	89 1.7	W
Junction & Storage temperature Range		$T_J, T_{STG}$	-55~+150	$^\circ C$

Notes : 1. EAS was tested at  $T_j = 25^\circ C$ ,  $L = 0.5mH$ ,  $I_d=-29A$ ..

### THERMAL CHARACTERISTICS

Characteristic	Condition	Symbol	Value	Unit
Thermal resistance,	Junction to Ambient Junction to Case	$R_{\theta JA}$ $R_{\theta JC}$	75 1.4	$^\circ C/W$

ELECTRICAL CHARACTERISTICS (at  $T_J = 25\text{ }^\circ\text{C}$ , unless otherwise specified)

Characteristic	Symbol	Min.	Typ.	Max.	Unit
Drain-Source Breakdown Voltage VGS = 0V, ID = -250uA	$V_{(BR)DSS}$	-40			V
Zero Gate Voltage Drain Current VDS = -40 V, VGS = 0 V	$I_{DSS}$			-1	uA
Gate-Source Leakage Current VGS = $\pm 20$ V, VDS = 0V	$I_{GSS}$			$\pm 100$	nA
Gate-Source threshold voltage VDS = VGS, ID = -250uA	$V_{GS(th)}$	-1.0		-2.0	V
Drain-Source On-State Resistance VGS = -10V, ID = -40A VGS = -4.5V, ID = -40A	$R_{DS(on)}$		6.5 8.5	7.8 11	m $\Omega$
Transconductance VDS = -5V, ID = -40A	$G_{fs}$		80		S
Input capacitance f=1MHz, VDS= -20 V, VGS=0 V	$C_{iss}$		3401		pF
Output capacitance f=1MHz, VDS= -20 V, VGS=0 V	$C_{oss}$		982		pF
Reverse transfer capacitance f=1MHz, VDS= -20 V, VGS=0 V	$C_{rss}$		47		pF
Total Gate Charge VDS= -20V, ID= -40A, VGS= -10V	$Q_G$		50		nC
Gate to Source Charge VDS= -20V, ID= -40A, VGS= -10V	$Q_{GS}$		7		nC
Gate to Drain Charge VDS= -20V, ID= -40A, VGS= -10V	$Q_{GD}$		7		nC
Turn-on delay time VDD= -20 V, VGS= -10V, ID= -40A, $R_{G\_ext}=3\Omega$	$t_{d(ON)}$		13		ns
Rise time VDD= -20 V, VGS= -10V, ID= -40A, $R_{G\_ext}=3\Omega$	$t_r$		94		ns
Turn-off delay time VDD= -20 V, VGS= -10V, ID= -40A, $R_{G\_ext}=3\Omega$	$t_{d(OFF)}$		66		ns
Fall time VDD= -20 V, VGS= -10V, ID= -40A, $R_{G\_ext}=3\Omega$	$t_f$		99		ns

## Body Diode

ELECTRICAL CHARACTERISTICS (at  $T_J = 25\text{ }^\circ\text{C}$ , unless otherwise specified)

Characteristic	Symbol	Min.	Typ.	Max.	Unit
Diode Forward Voltage $V_{GS} = 0V, I_S = -20A$	$V_{SD}$			-1.2	V
Maximum Continuous Body Diode Forward Current	$I_S$			-85	A
Revers Recovery Time $I_F = -20A, di/dt = -100A/\mu s$	$T_{rr}$		49		ns
Revers Recovery Charge $I_F = -20A, di/dt = -100A/\mu s$	$Q_{rr}$		52		nC

Typical Performance Characteristics

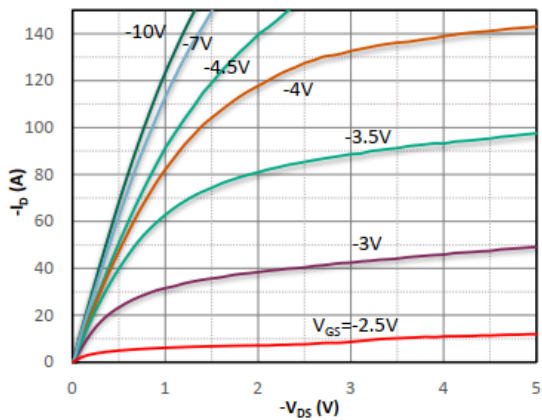


Figure 1 Output Characteristics

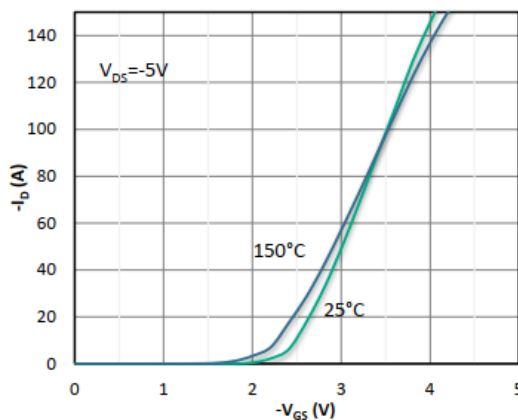


Figure 2. Transfer Characteristics

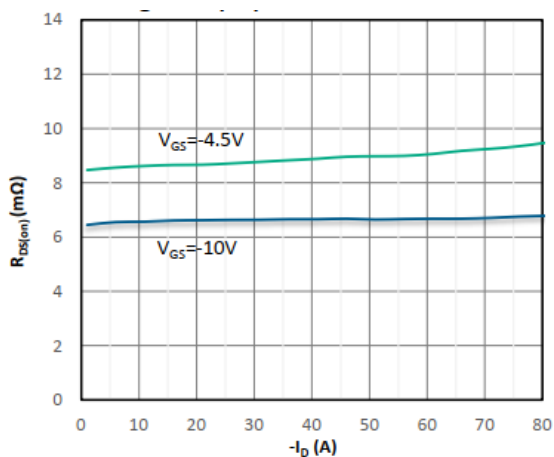


Figure 3. Rds(on) vs Drain Current

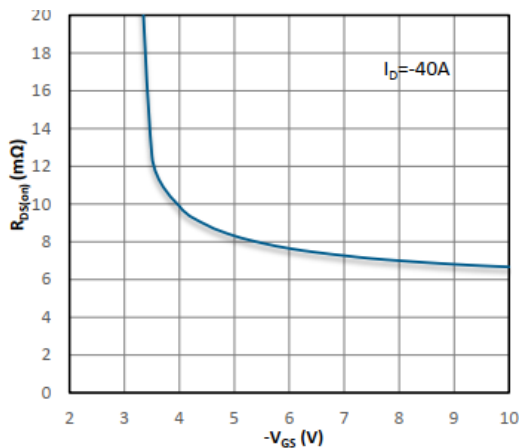


Figure 4. Rds(on) vs Gate Voltage

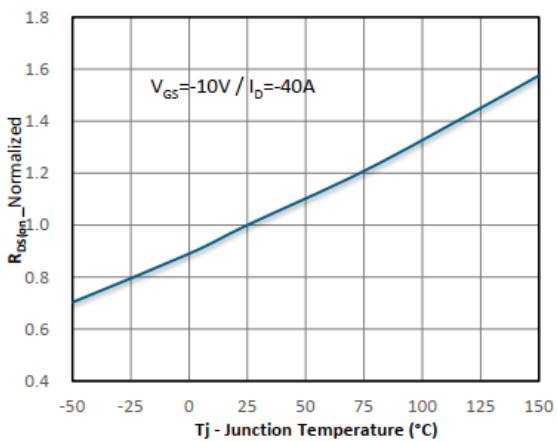


Figure 5. Rds(on) vs. Temperature

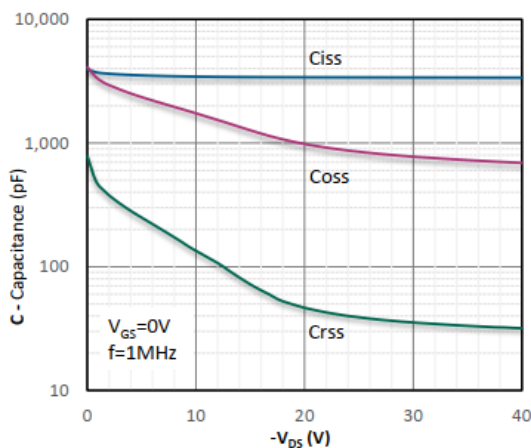


Figure 6. Capacitance Characteristics

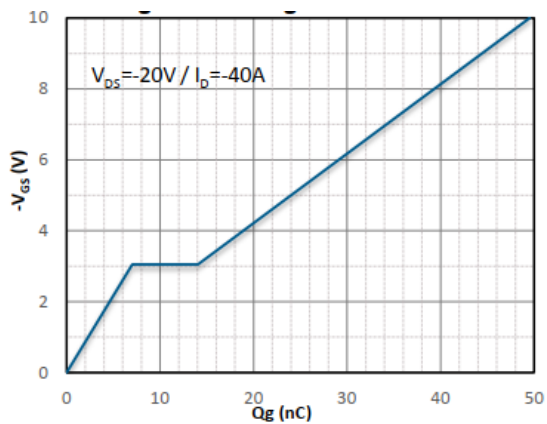


Figure 7. Gate Charge Characteristics

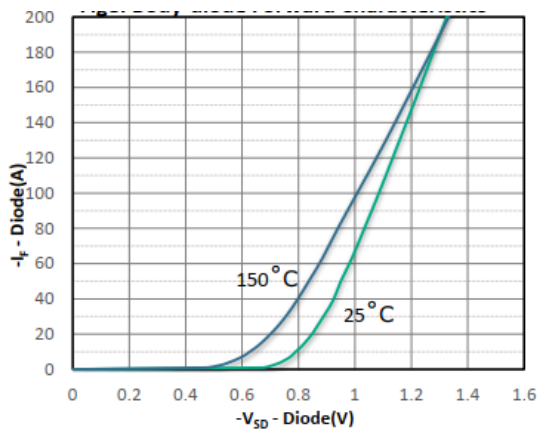


Figure 8. Body-diode Forward Characteristics

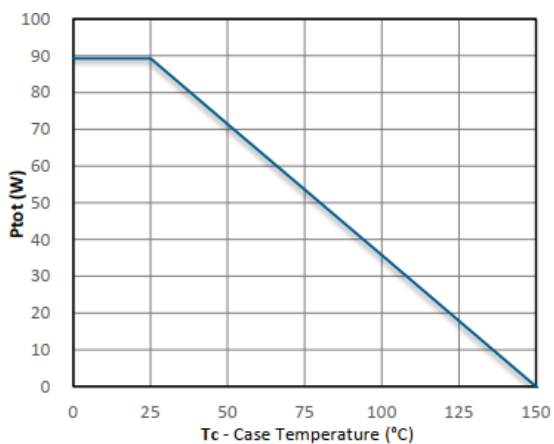


Figure 9. Power De-rating

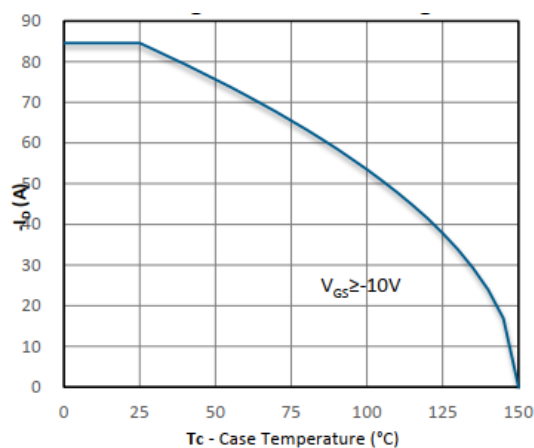


Figure 10. Current De-rating

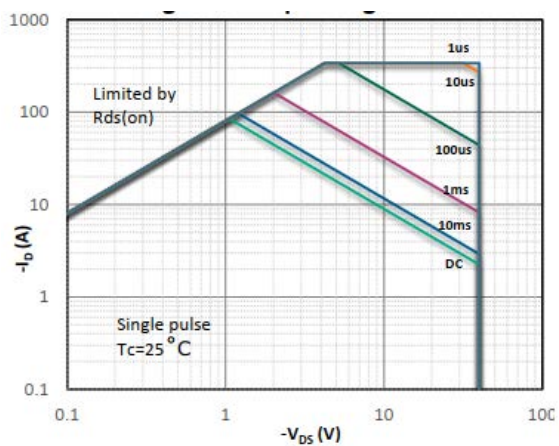


Figure 11. Safe Operating Area

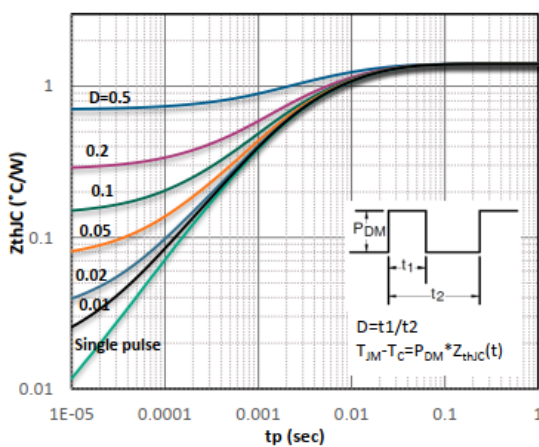
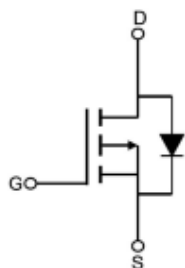
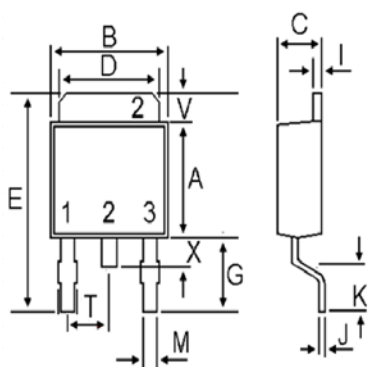


Figure 12. Max. Transient Thermal Impedance

- Circuit diagram



- Package outlines : Dimensions in (mm)



DIM	MILLIMETERS	
	MIN	MAX
A	5.97	6.22
B	6.30	6.75
C	2.18	2.40
D	4.95	5.50
E	9.40	10.41
G	2.75	3.20
I	0.46	0.89
J	0.46	0.61
K	1.40	1.78
M	0.64	0.89
T	2.18	2.38
V	0.89	1.27
X	---	1.05

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